

Amend the paragraph beginning at page 6, line 37
to read as follows.

FIG. 4 is a schematic top perspective view of a support pedestal 140 configured in accordance with the present invention. The inventive support pedestal 140 comprises a support frame 145 having a plurality of support legs 141 extending downward therefrom. The support frame 145 has a frame outline which substantially duplicates the bottom outline of the mainframe 117 of the manufacturing equipment 111, with the "bottom outline" of the mainframe 117 being defined by the lower frame of the mainframe 117 itself. In one aspect the support frame 145 may be monolithic so as to provide the enhanced support integrity which comes from a "seamless" frame. The support frame 145 includes brackets 147 for engaging the load-bearing mounting feet of the manufacturing equipment (if any). The support legs 141 are adjustable and comprise an outer leg section 144 fixedly mounted (e.g., bolted or welded) to the support frame 145, and an inner leg section 142. The inner leg section 142 is slideably mounted in the outer leg section 144, so that the length of the support legs 141 can be adjusted and, once optimized, locked in place by bolting or welding the inner leg section 142 to the first outer leg section 144. The support legs 141 are disposed on base mount location pads 143, which can be affixed (e.g., removably via bolts, or welded) to the support legs 141 prior to installation or can be provided at the installation site. Additionally affixed to the support legs 141 are optional seismic braces 149. A first end of each seismic brace 149 is fixedly mounted to a support leg 141 as shown, (or alternatively could be attached directly to the waffle grid flooring) while a second end of

cont. 10
the seismic brace 149 is provided for attachment to the manufacturing equipment 111 upon installation thereof.

Amend the paragraph beginning at page 7, line 30 to read as follows.

A3
The inventive support pedestal 140 includes at least one facilities connection locator 150 which is fixedly mounted to the support frame 145 and which establishes the facilities connection locations, representatively shown as the four facilities connection locations 151-154, which exactly match the facilities connection points on the manufacturing equipment 111. Optional outer flanges 158 (FIG. 4A, not shown in FIG. 4) at the periphery of the support frame 145, as well as optional inner flanges 159 (not shown in FIG. 4) are provided for supporting raised flooring (as shown in FIG. 5).

Amend the paragraph beginning at page 9, line 16 to read as follows.

ad
The support pedestal 140 is adaptable to specific manufacturing equipment configurations, as illustrated in FIG. 6. For the installation of a semiconductor processing system, such as is depicted in FIG. 1, which includes not only the mainframe processing unit 117 but also the factory interface 114 with loadlocks 113 and 115 and a process chamber 119, the support pedestal 140 can be augmented with at least one additional support 160, including an additional frame 165 supported by additional support legs 161 extending to additional base mount location pads 163 to support the factory interface 114, the loadlocks 113, 115 or the processing chamber 119 (FIG. 1). The components of the additional support 160 may be configured in the same manner

cmf
a4

as the components of the support pedestal 140 with adjustable legs 161 positioned below load bearing mounting of the manufacturing equipment positioned on the additional support 160 and/or frame 165 that duplicates the bottom of the manufacturing equipment. The additional support component 160 may be joined to the support pedestal 140 by connecting segments 167. Alternatively, however, the pedestal frame 145 can be extended to include the support for the additional manufacturing equipment (e.g., the processing chamber 119). Thus, a single support pedestal 140 may be configured to support one or more pieces of manufacturing equipment or a plurality of support pedestals may be coupled directly or via a connecting segment 167. In this example of FIG. 6, the support pedestal 140 includes an additional facilities connection locator 170 with additional facilities connection locations (171 of FIG. 8) as needed (e.g., for the additional processing chamber 119).

In the Claims:

Cancel non-elected claims 14-19 without prejudice.

Amend claims 1, 8, 9, 11, 13 and 20 to read as follows.

- SUB
B1
- a5
1. (Amended) Support apparatus for an installation of semiconductor processing equipment having a bottom outline and a plurality of load-bearing mounting feet disposed along the equipment's bottom outline comprising:
- a plurality of support legs including at least one support leg aligned to each one of the plurality of load-bearing mounting feet; and
 - a frame disposed on the plurality of support legs, the frame having a frame outline which substantially duplicates the bottom outline of the semiconductor processing